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Mollich

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Trivedi et al.

Appl. No. : 10/038,305

Filed : January 2, 2002

For : METHOD OF FORMING A
DUAL DAMASCENE
INTERCONNECT (As
Amended Herewith)

Examiner : T. Nguyen

) Group Art Unit 2813

) I hereby certify that this correspondence and all
) marked attachments are being deposited with the
) United States Postal Service as first-class mail in
) an envelope addressed to: United States Patent
) and Trademark Office, P.O. Box 2327,
) Arlington, VA 22202, on

) November 20, 2002

) (Date)

) *Adeel S. Akhtar*

) Adeel S. Akhtar, Reg. No. 41,394

AMENDMENT AND RESPONSE TO OFFICE ACTIONUnited States Patent and Trademark Office
P.O. Box 2327
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed on August 28, 2002, please amend the above-captioned application as follows:

IN THE SPECIFICATION:

✓ Please amend the title paragraph beginning on page 1, line 2 as follows:

METHOD OF FORMING A DUAL DAMASCENE INTERCONNECT

IN THE CLAIMS:

Please amend the following claim:

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11. (Amended) A method for fabricating an integrated circuit interconnect structure, comprising:

etching a pattern of dual damascene trenches and contact vias in insulating material;

preferentially depositing a first metal into the contact vias to partially fill the contact vias; and